

Amendments to the Specification:

Please replace the paragraph, beginning at page 1, line 20, with the following rewritten paragraph:

In the LPF, the printed electrode patterns are located as close to each other as possible in order to allow the device to have a reduced size. The LPF, having an excessively reduced size, as shown by solid line [[E]]E of Fig. 14, does not suppress high frequency bands sufficiently. This is caused due to mutual magnetic interference particularly between the inductors 104 and 105. Dotted line [[F]]E shows an ideal characteristic of the LPF without the mutual magnetic interference.

Please replace the paragraph, beginning at page 7, line 13, with the following rewritten paragraph:

In the LPF of Embodiment 2, magnetic sheet 1b and dielectric sheet 101c having patterns 6, 7, and 8 are stacked and sintered to provide a laminated body. If respective materials of the dielectric sheet and the magnetic sheet diffuse into each other during the sintering, the sheets may change in their electrical and mechanical properties, i.e., dielectric constant and permeability, increase of material loss, and deterioration of mechanical strength. The diffusion prevents reliable high frequency laminated devices from being manufactured. In the LPF of Embodiment 2, capacitor patterns 6, 7, and 8 each having a large plane are formed at an interface between the magnetic sheet 1b and the dielectric sheet 101c which form the laminated body suppress the diffusion at the interface between the magnetic sheet 1b and the dielectric sheet 101c. That is, in the LPF of Embodiment 2, [[a]]capacitor patterns having large areas are formed at the interface between different materials, i.e., magnetic sheet 1b and dielectric sheet 101c. This arrangement configures a capacitor in the laminated body and provides the reliable LPF, i.e., the high frequency laminated device.

Please replace the paragraph, beginning at page 8, line 2, with the following rewritten paragraph:

According to Embodiment 2, the capacitor pattern is formed between the dielectric sheet 101c and the magnetic sheet 1b. However, a land-form pattern having no electrical connections may provide[[s]] the same effects. An inductor pattern may be formed at a portion of the interface.

Please replace the paragraph, beginning at page 9, line 17, with the following rewritten paragraph:

The duplexer of Embodiment 3, including the laminated body 11 having the magnetic sheets, increases [[an]]the isolation between inductor patterns forming inductors similarly to Embodiments 1 and 2, thus providing the duplexer with ideal characteristics. The inductor patterns being relatively short but not thin provides the inductors with large inductances, thus allowing the duplexer to have a small size and a small insertion loss. A high frequency device including many circuit elements like the duplexer of Embodiment 3 includes a lot of inductor patterns and capacitor patterns, that is, a lot of patterns coupled electro-magnetically to each other. The laminated body including different materials, i.e., a dielectric sheet and a magnetic sheet, can include[[s]] a large capacitor pattern formed at a interface between the materials, thus emphasizing effects of Embodiment 2.